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M-9950 US

STACKABLE LEAD FRAME PACKAGE USING EXPOSED INTERNAL
LEAD TRACES

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ABSTRACT

10 A die package is formed, which allows additional
electrical connections to the die by using internal
leads or traces from a lead frame. The internal leads
are exposed through an upper or lower surface of the
package, thereby allowing an additional die package to
be stacked and electrically connected to the underlying
die or additional inputs/outputs to underlying external
circuitry, such as a printed circuit board.

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TOP SECRET